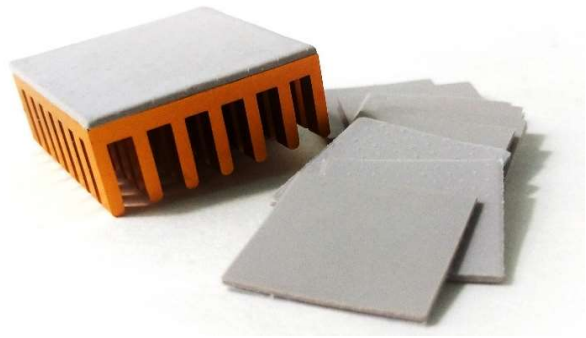
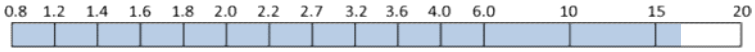
TG-A1660
Ultra Soft Thermal Pad

REACH RoHS UL



Features
High thermal conductivity
Low thermal resistance
Electrical insulation

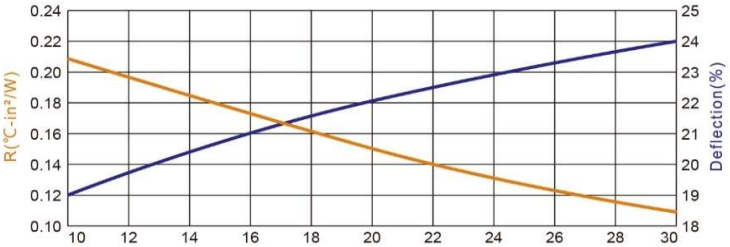
Thermal Conductivity : 16.6 W / mK



Hardness : 65 (Shore 00)

Applications
Best for high power applications
Electronic components: IC, CPU, MOS, LED, Mother Board,Power Supply,Heat Sink,LCD-TV,Notebook,PC,Telecom Device,Wireless Hub,DDR II Module, DVD Applications, Hand-set applications etc.

Thermal Resistance VS. Pressure VS. Deflection



Pressure (psi)	R (°C-in²/W)	Deflection (%)
10	0.209	19
30	0.112	24

Properties

Properties	TG-A1660	Unit	Tolerance	Test Method
Thermal Conductivity	16.6	W / mK	±1.6	ASTM D5470
Thickness	0.5~2.0	mm	-	ASTM D374
	0.0197~0.0787	inch	-	ASTM D374
Color	Dark Gray	-	-	Visual
Flame Rating	V-0	-	-	UL 94
Dielectric Breakdown Voltage	5	KV / mm		ASTM D149
Weight Loss	<1	%	-	ASTM E595
Density	3.6	g / cm^3		ASTM D792
Working Temperature	-50 ~ +150	°C	-	-
Volume Resistance	5x10^{12}	Ohm-m	-	ASTM D257
Elongation	20	%	-	ASTM D412
Standard Shape	Sheet ones單片狀	-	-	-
Hardness	65	Shore 00	±5	ASTM D2240
Need samples?	**Pre-cut for different shapes**			

T-Global Techonology Co., Ltd
Provide professional thermal engineering solutions and full range of products.
No. 33, Ln. 50, Daren Rd., Taoyuan Dist., Taoyuan City 330, Taiwan
T: +886-3-3618899 **M**: service@tglobal.com.tw **W**: www.tglobalcorp.com

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Matlog – Partner & Exclusive representative – +33 2 41 48 79 50 – thomas.morvan@matlog.com